

| L Number | Hits | Search Text   | DB  | Time stamp       |
|----------|------|---|---|------------------|
| -        | 8    | ((("5892288") or ("6216937") or ("6287949") or ("6301121"))).PN.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/25 16:45 |
| -        | 9296 | (257/779,723,778,747,669,678,737,700,783).CCLS.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/26 05:17 |
| -        | 2896 | (438/106,121).CCLS.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/26 05:17 |
| -        | 1926 | (multi-chip multi?chip multi adj chip) and mount\$3 near3 board   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/26 05:08 |
| -        | 523  | ((multi-chip multi?chip multi adj chip) and mount\$3 near3 board) and electrode   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/25 16:48 |
| -        | 235  | ((multi-chip multi?chip multi adj chip) and mount\$3 near3 board) and electrode) and interconnect\$3                              | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/25 16:49 |
| -        | 5    | ((multi-chip multi?chip multi adj chip) and mount\$3 near3 board) and electrode) and interconnect\$3) and stress near3 relaxat\$3 | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/26 04:42 |
| -        | 2    | ("6696765").PN.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/26 04:44 |
| -        | 0    | 10/700470   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/26 04:44 |
| -        | 39   | (multi-chip multi?chip multi adj chip) and stress near3 relaxat\$3  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/26 05:10 |
| -        | 9    | (multi-chip multi?chip multi adj chip) and ((stress near3 relaxat\$3) with thick\$4)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/26 05:17 |
| -        | 9296 | (257/779,723,778,747,669,678,737,700,783).CCLS.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/26 05:17 |

|   |      |   |   |                  |
|---|------|---|---|------------------|
| - | 2896 | (438/106,121).CCLS.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/26 05:17 |
| - | 3    | ((438/106,121).CCLS.) and ((stress near3 relaxat\$3) with thick\$4)                             | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/26 05:17 |
| - | 19   | ((257/779,723,778,747,669,678,737,700,783).CCLS.) and ((stress near3 relaxat\$3) with thick\$4) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/26 05:52 |
| - | 1    |   | USPAT   | 2004/03/26 05:45 |
| - | 1    |   | USPAT   | 2004/03/26 05:45 |
| - | 1    |   | USPAT   | 2004/03/26 05:46 |
| - | 1    |   | USPAT   | 2004/03/26 05:46 |
| - | 1    |   | USPAT   | 2004/03/26 05:46 |
| - | 1    |   | USPAT   | 2004/03/26 05:46 |
| - | 19   | "126044"  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/26 05:53 |

(8) ("5892288") or ("6216937") or ("6287949") or ("6  
(9296) (257/779,723,778,747,669,678,737,700,783). C  
(2896) (438/106,121). CCLS.  
(1926) (multi-chip multi?chip multi adj chip) and moun  
(523) ((multi-chip multi?chip multi adj chip) and moun  
(235) (((multi-chip multi?chip multi adj chip) and moun  
(5) ((((multi-chip multi?chip multi adj chip) and mount  
(2) ("6696765").PN.  
(0).10/700470  
(39) (multi-chip multi?chip multi adj chip) and stress n  
(9) (multi-chip multi?chip multi adj chip) and ((stress r  
(9296) (257/779,723,778,747,669,678,737,700,783). C  
(2896) (438/106,121). CCLS.  
(3) ((438/106,121). CCLS.) and ((stress near3 relaxat\$3  
(19) ((257/779,723,778,747,669,678,737,700,783). CC  
(1) "5892288".PN.  
(1) "6216937".PN.  
(1) "5669545".PN.  
(1) "6216937".PN.

|  |  |        |       |   |
|--|--|--------|-------|---|
| Search   | Clear  | Browse | Queue | Clear   |
| DBs  | USPAT, US-PGPUB, EPO, JPO, DERWENT, IBM, TDB |        |       | <input checked="" type="checkbox"/> Plurals                           |
| Default operator:  | OR   |        |       | <input checked="" type="checkbox"/> Highlight all hit terms initially |
| ((257,779,723,778,747,669,678,737,700,783) CCLS.) and ((stress near3<br>relaxat\$3) with thick\$4) |  |        |       |   |

|    | U | I | Document ID   | Issue Date | Pages | Title                    | Current | Cur Re | Inventor             | S | C | P | 2 | 3 |
|----|---|---|---------------|------------|-------|--------------------------|---------|--------|----------------------|---|---|---|---|---|
| 11 | □ | □ | US 6710446 B2 | 20040323   | 20    | Semiconductor device co  | 257/737 | 257/   | Nagai, Akira et al.  | □ | □ | □ | □ | □ |
| 12 | □ | □ | US 6696765 B2 | 20040224   | 14    | Multi-chip module        | 257/779 | 257/   | Kazama, Atsushi et   | □ | □ | □ | □ | □ |
| 13 | □ | □ | US 6696764 B2 | 20040224   | 30    | Flip chip type semicondu | 257/778 | 257/   | Honda, Hirokazu      | □ | □ | □ | □ | □ |
| 14 | □ | □ | US 6624504 B1 | 20030923   | 43    | Semiconductor device an  | 257/668 | 257/   | Inoue, Kosuke et al. | □ | □ | □ | □ | □ |
| 15 | □ | □ | US 6621170 B2 | 20030916   | 24    | Semiconductor device, s  | 257/783 | 156/   | Yamamoto, Kazuno     | □ | □ | □ | □ | □ |
| 16 | □ | □ | US 6396145 B1 | 20020528   | 21    | Semiconductor device an  | 257/737 | 228/   | Nagai, Akira et al.  | □ | □ | □ | □ | □ |